



# Pixel 2008 International Workshop

## Thursday, 25 September 2008

### 3D Bonding - One West (10:50 - 12:30)

time	[id] title	presenter
10:50	[78] Test Results from the VIP Chip	DEPTUCH, Grzegorz
11:15	[79] Fabrication, Assembly, and Evaluation of Cu-Sn and Cu-Cu Bump Bonding arrays for Ultra-Fine Pitch Hybridization and 3D Integration	HUFFMAN, Alan
11:40	[80] Status and perspectives of Deep N-Well 130 nm CMOS MAPS	Prof. RE, Valerio
12:05	[81] Analysis of 3D Stacked, Fully Functional CMOS Active Pixel Sensor Detectors	Dr PASSERI, Daniele